



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ PLCC2 SMD
- ▶ 2835 1W Series
- ▶ Warm White (3000K)

NOW15S57



Release Date: 18 June 2015 Version: A1.1



2835 1W Series



FEATURES:

- **Package:** PLCC2 High Power White SMT Package
- **Forward Current:** 120mA
- **Forward Voltage (typ.):** 6.4V
- **Luminous Flux (typ.):** 85lm @120mA
- **Colour:** Warm White
- **Colour Temperature:** 3000K
- **Viewing angle:** 120°
- **Materials:**
 - Die: InGaN
 - Resin: Silicon (Yellow Diffused)
 - L/T Finish: Ag plated
- **Operating Temperature:** -20~+80°C
- **Storage Temperature:** -30~+100°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous flux
 - CIE Chromaticity
- **Soldering methods:** IR Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with 2000/reel, ø180mm (7'')

APPLICATIONS:

- Decorative Lighting
- General Lighting
- Backlighting
- Indicator
- Display

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	150	mA
Peak Forward Current (Duty 1/10; width 10KHz)	I_{FP}	300	mA
Reverse Current @5V	I_R	50	μ A
Power Dissipation	P_D	1080	mW
Electrostatic Discharge	ESD	500	V
Junction Temperature	T_j	125	°C
Operating Temperature	T_{OPR}	-20~+80	°C
Storage Temperature	T_{STG}	-30~+100	°C
Soldering Temperature	T_{SD}	260	°C
Colour Rendering Index	CRI	>80	---

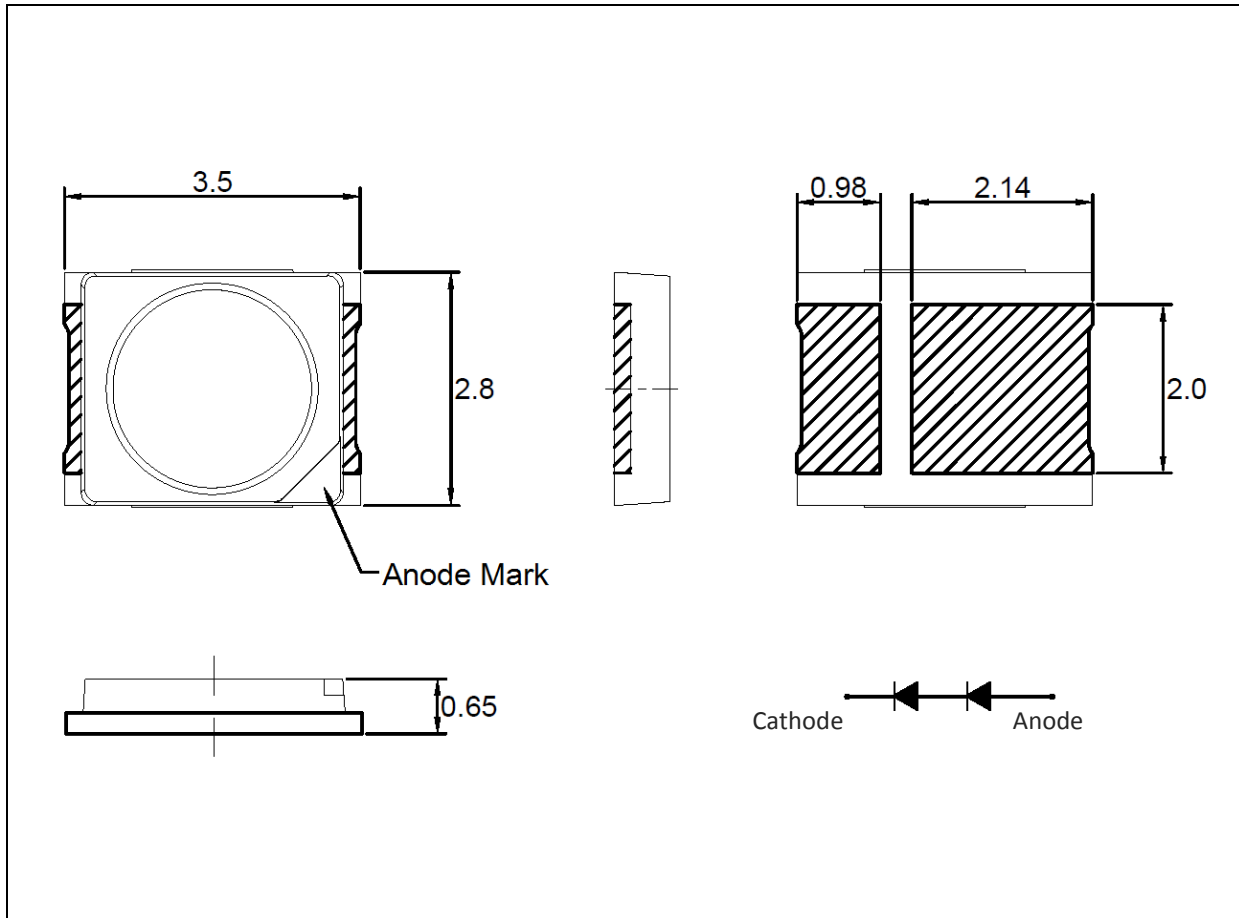
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	5.6	6.4	7.2	V	$I_F=120$ mA
Luminous Flux	Φ_{Iv}	80	85	100	lm	$I_F=120$ mA
Chromaticity Coordinates	X	0.4147	---	0.4562	---	$I_F=120$ mA
	Y	0.3814	---	0.4260		
Colour Temperature	CCT	2870	3000	3220	K	$I_F=120$ mA
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	$I_F=120$ mA

1. Luminous intensity (I_v) $\pm 15\%$, Forward Voltage (V_f) ± 0.1 V, Viewing angle($2\theta_{1/2}$) $\pm 5\%$
2. IS standard testing

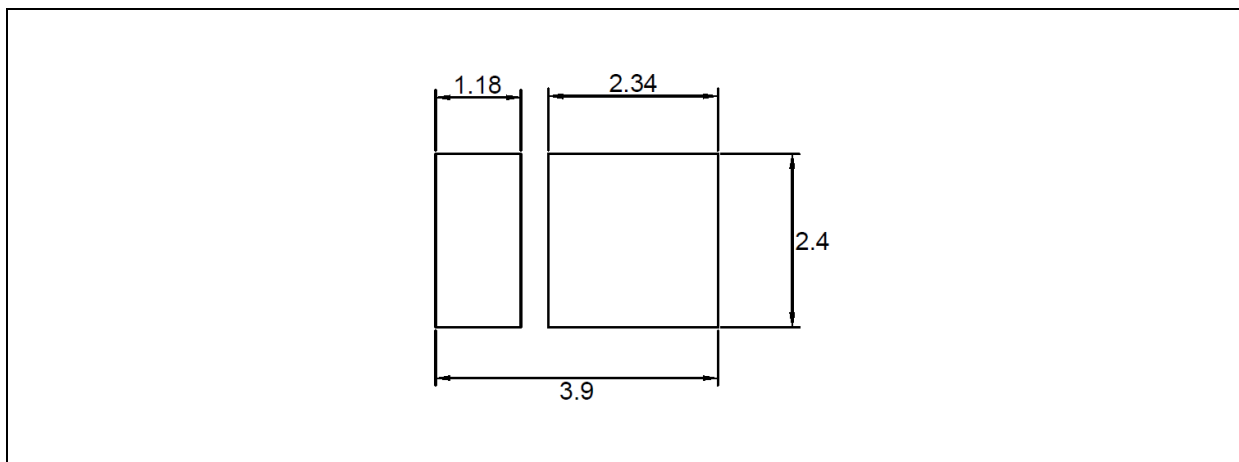
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.2 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^\circ$.

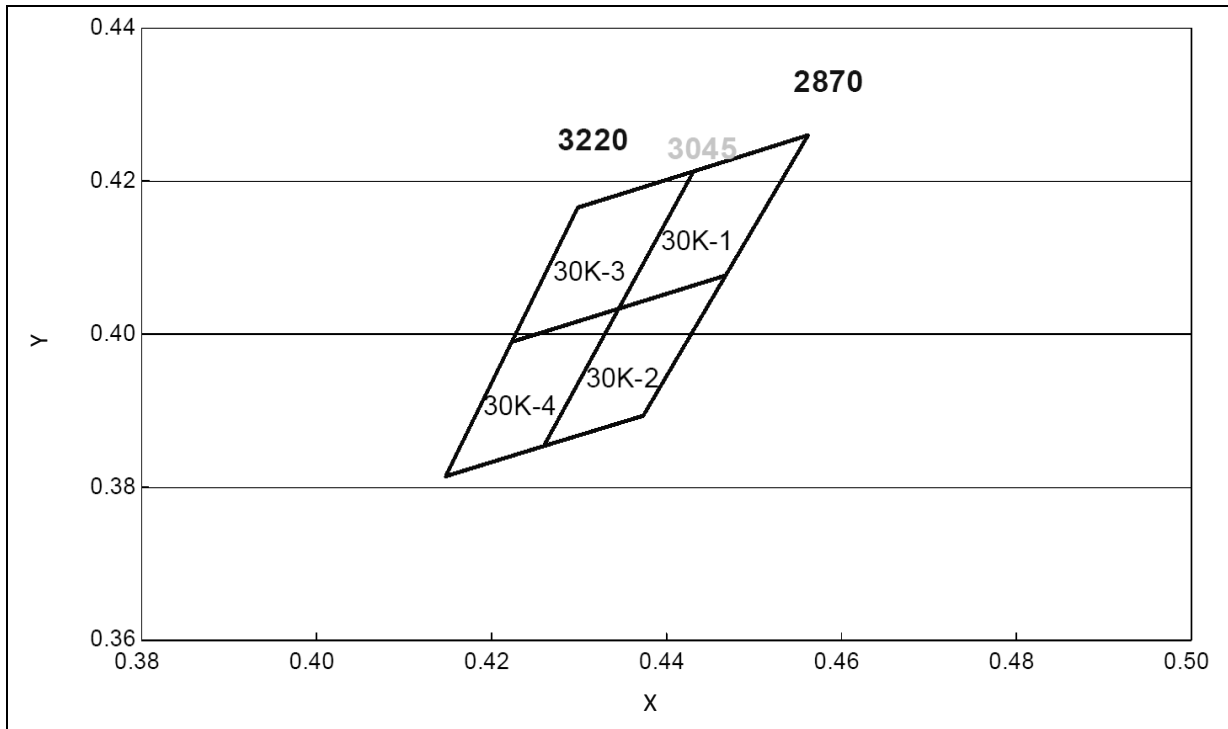
BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 120\text{mA}$):

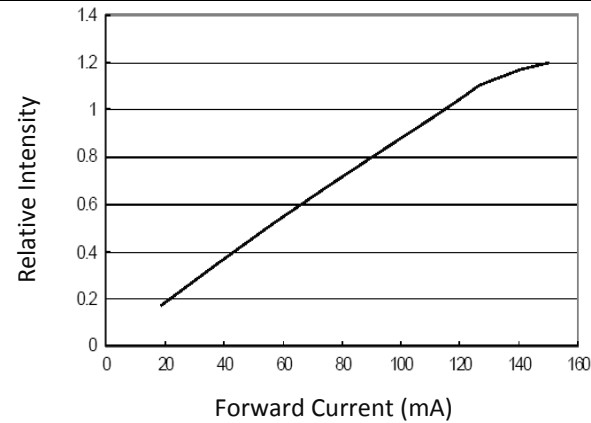
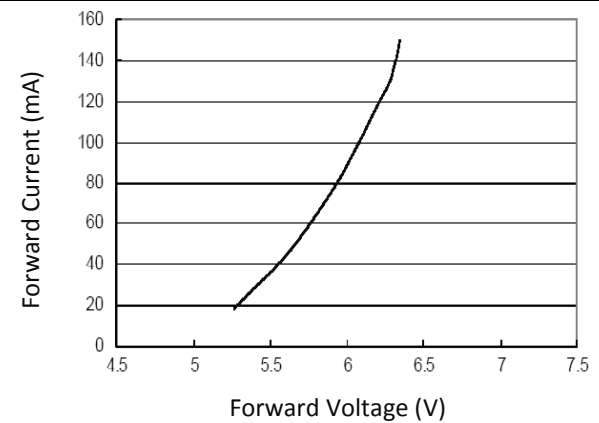
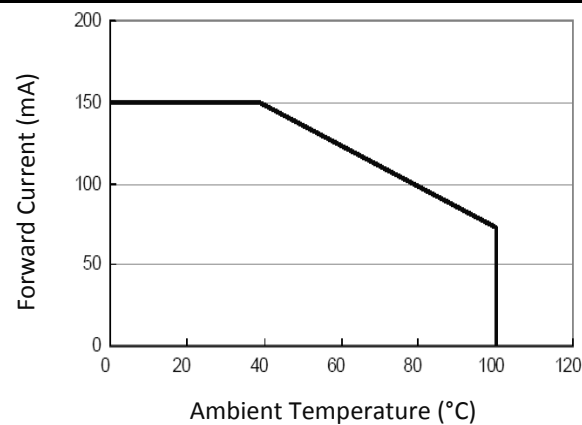
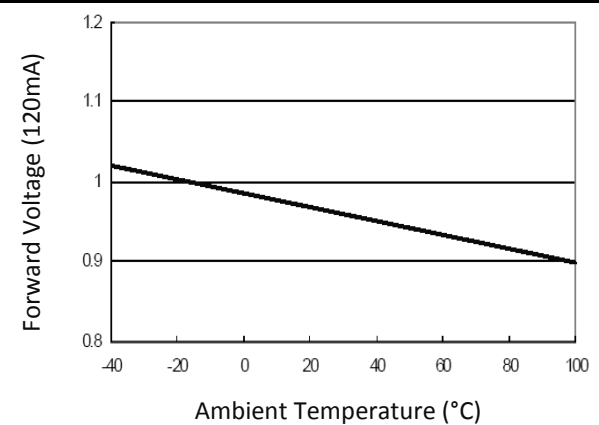
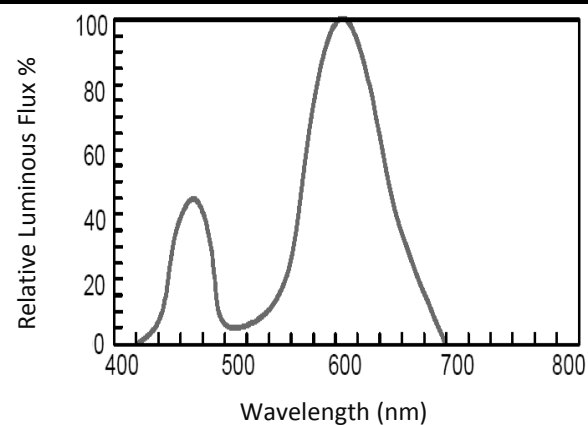
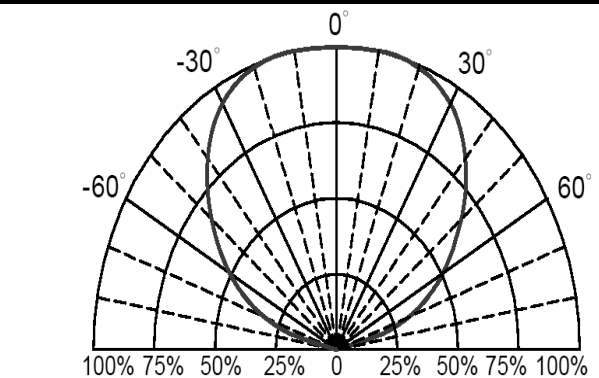
Code	Min.	Max.	Unit
1	5.6	5.8	V
2	5.8	6.0	
3	6.0	6.2	
4	6.2	6.4	
5	6.4	6.6	
6	6.6	6.8	
7	6.8	7.0	
8	7.0	7.2	

 Luminous Flux Classifications ($I_F = 120\text{mA}$):

Code	Min.	Max.	Unit
F80V	80	85	lm
F85V	85	90	
F90V	90	95	
F95V	95	100	

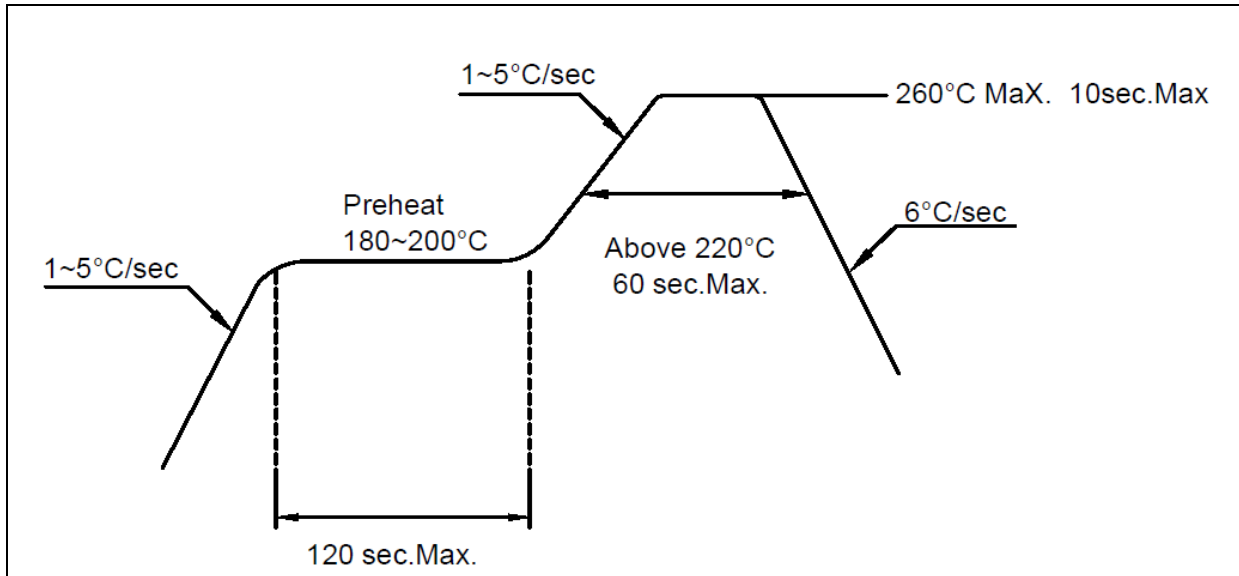
CIE CHROMATICITY DIAGRAM:

 Chromaticity Coordinates Classifications ($I_F = 120\text{mA}$):

	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
30K-1	0.4562	0.4260	0.4431	0.4213	0.4345	0.4033	0.4468	0.4077
30K-2	0.4468	0.4077	0.4345	0.4033	0.4260	0.3854	0.4373	0.3893
30K-3	0.4431	0.4213	0.4299	0.4165	0.4223	0.3990	0.4345	0.4033
30K-4	0.4345	0.40330	.4223	0.3990	0.4147	0.3814	0.4260	0.3854

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Luminous Flux v.s. Ambient Temp.

Forward Voltage v.s. Ambient Temp.

Luminous Spectrum

Directive Radiation


RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:

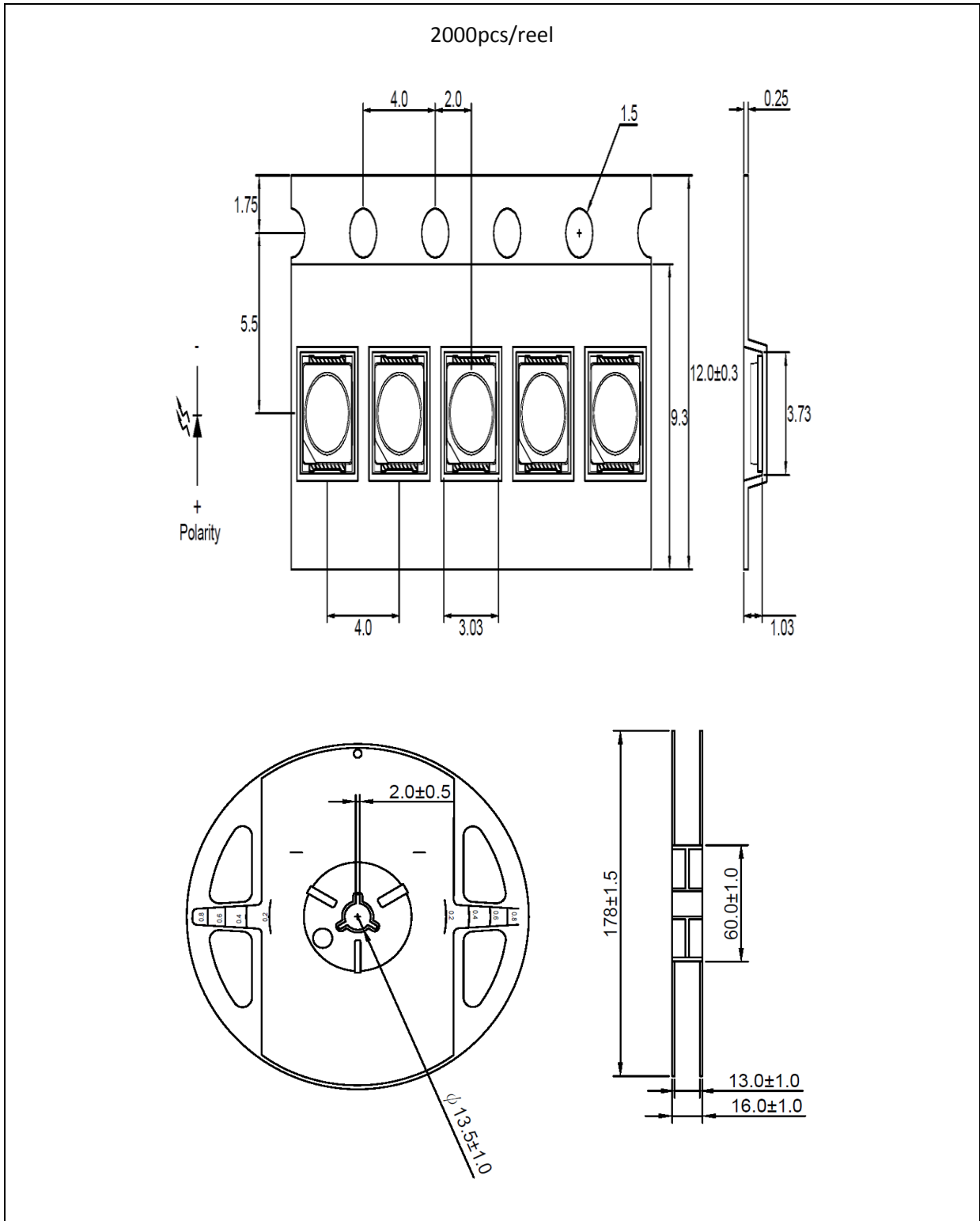


Note:

1. Maximum reflow soldering: 2 times.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.
3. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

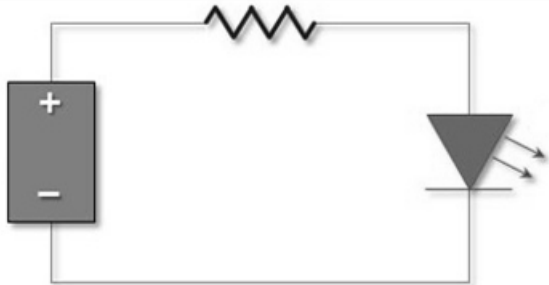
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs.

The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	26/11/2014	Datasheet set-up.
A1.1	18/06/2015	Revise Anode Mark location